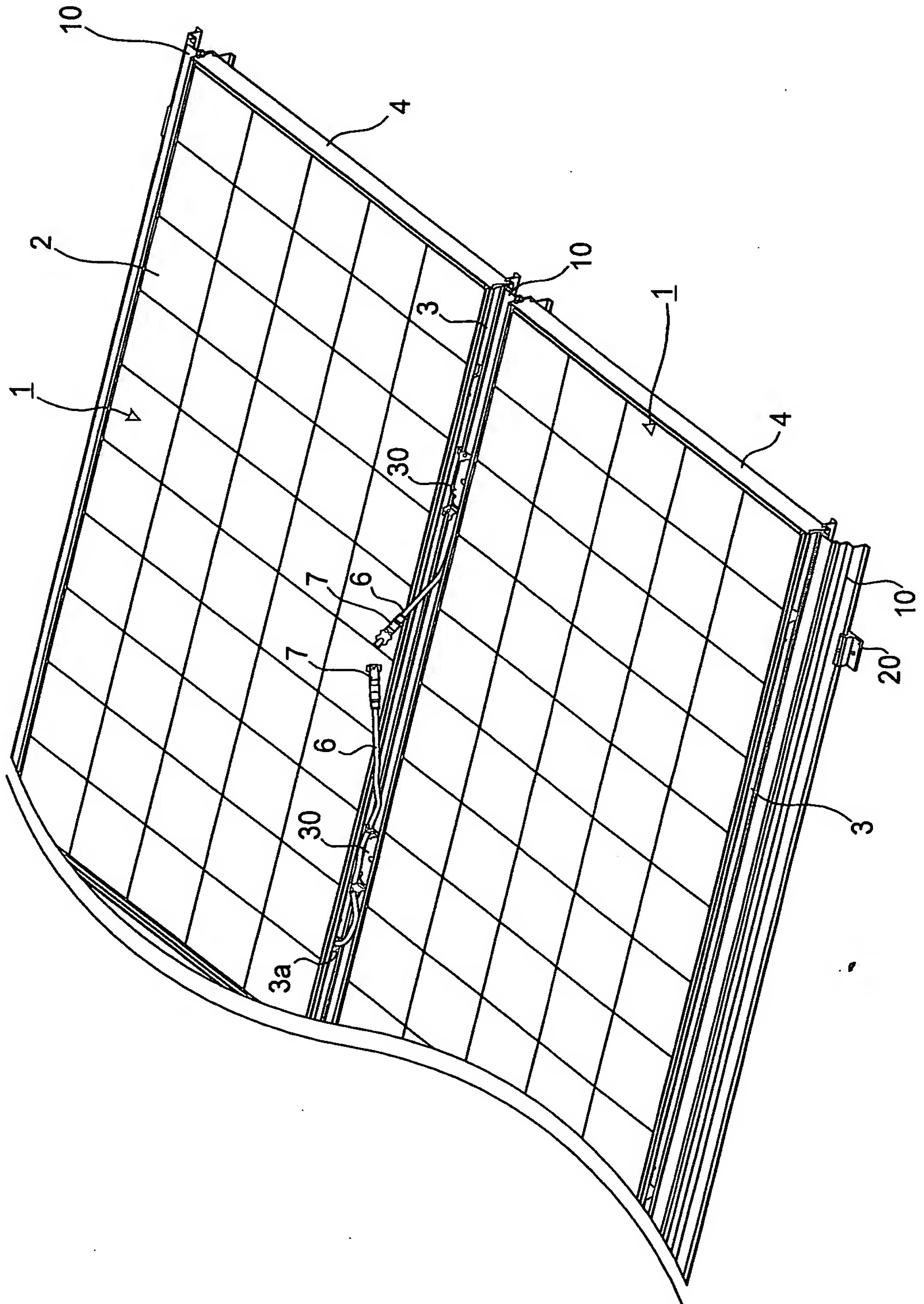
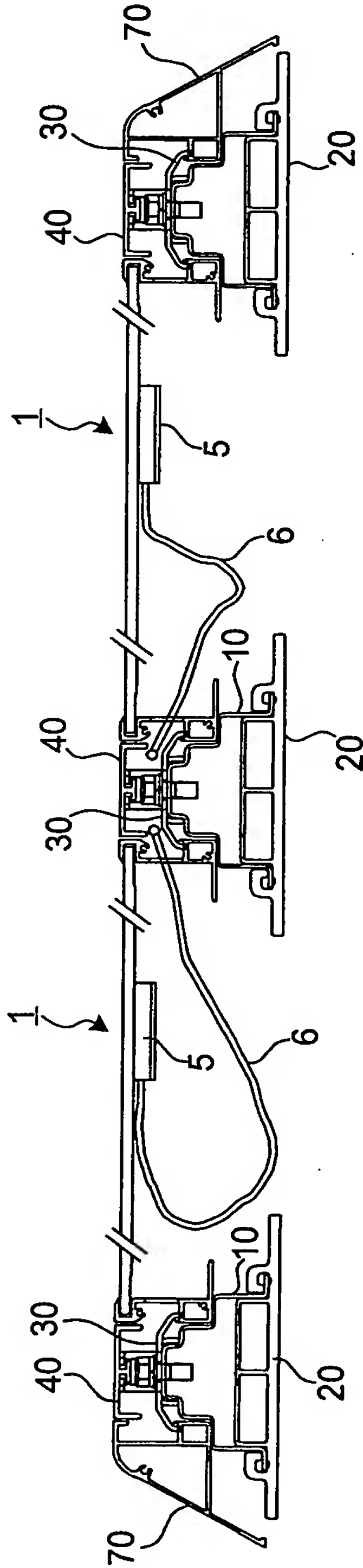


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FIG.3



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FIG.4

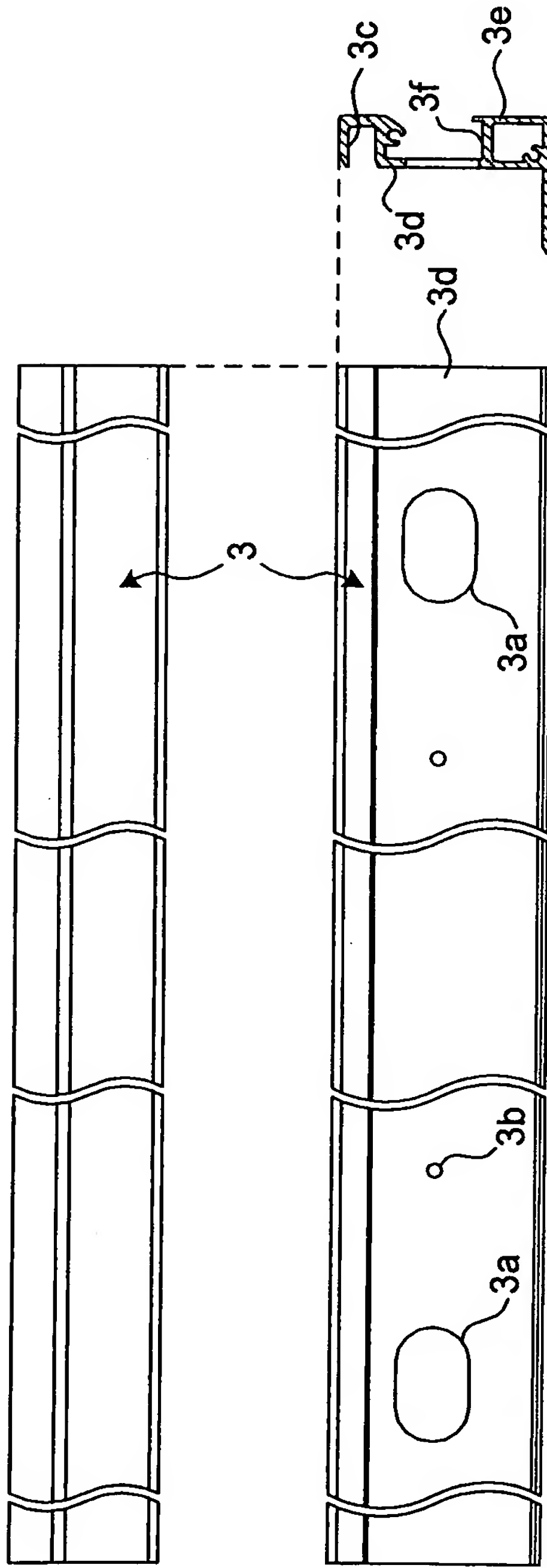
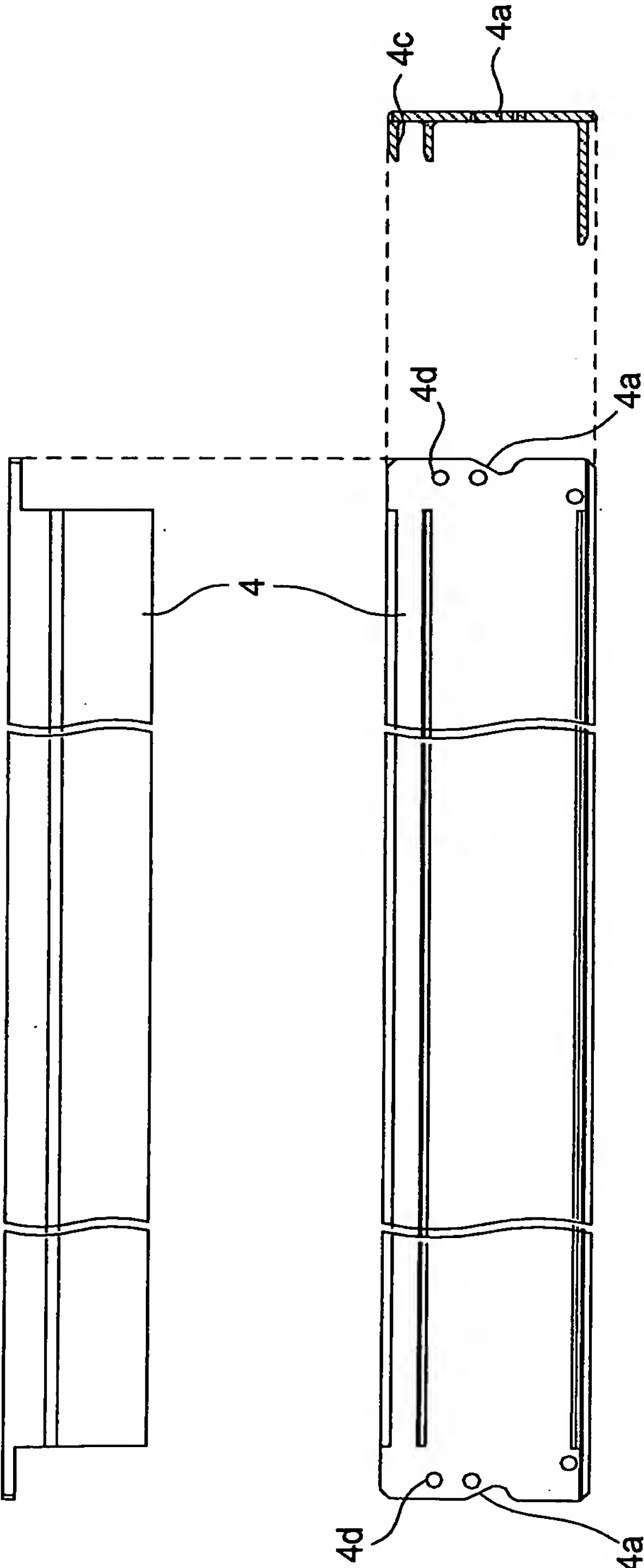


FIG.5





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FIG.7

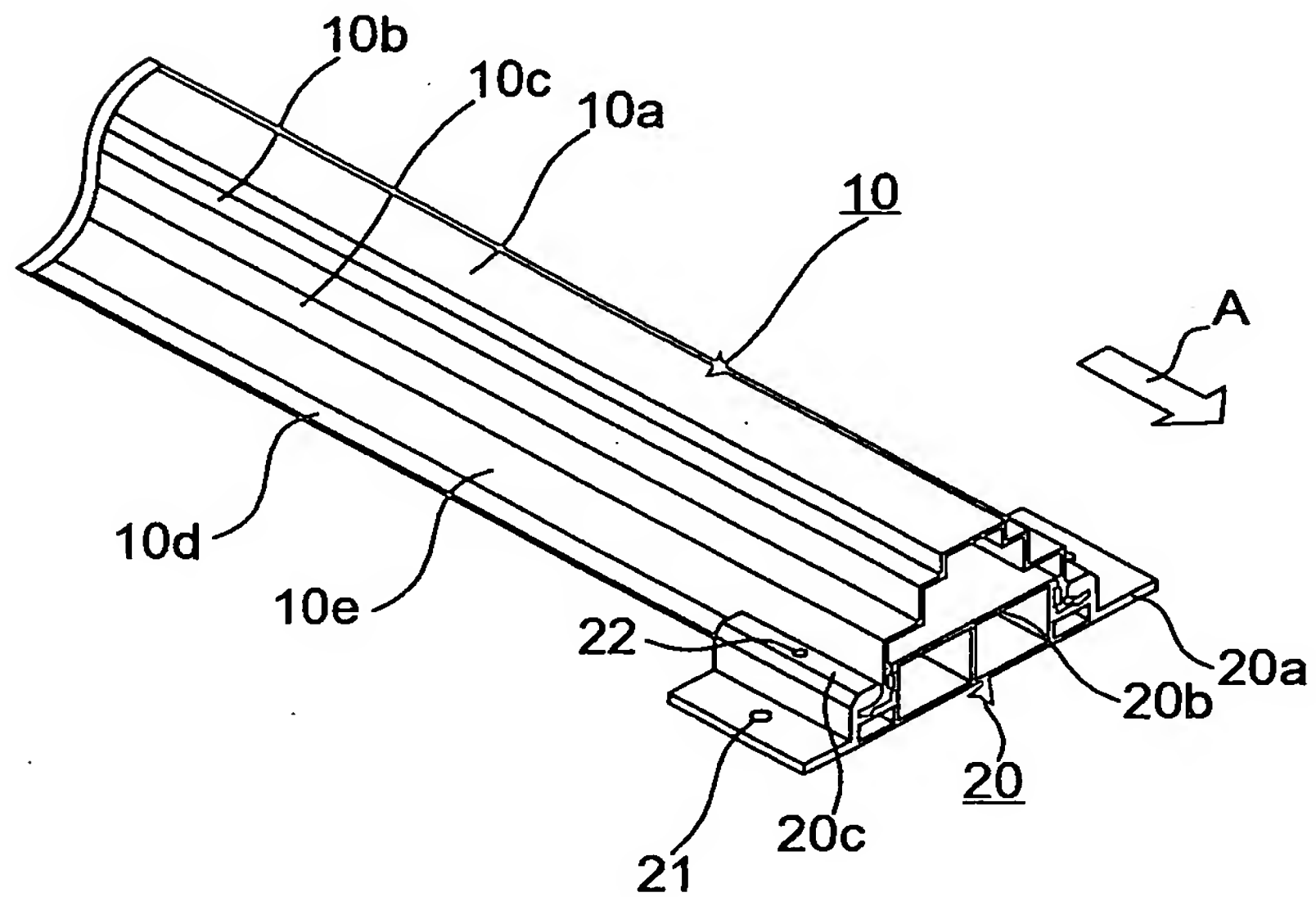
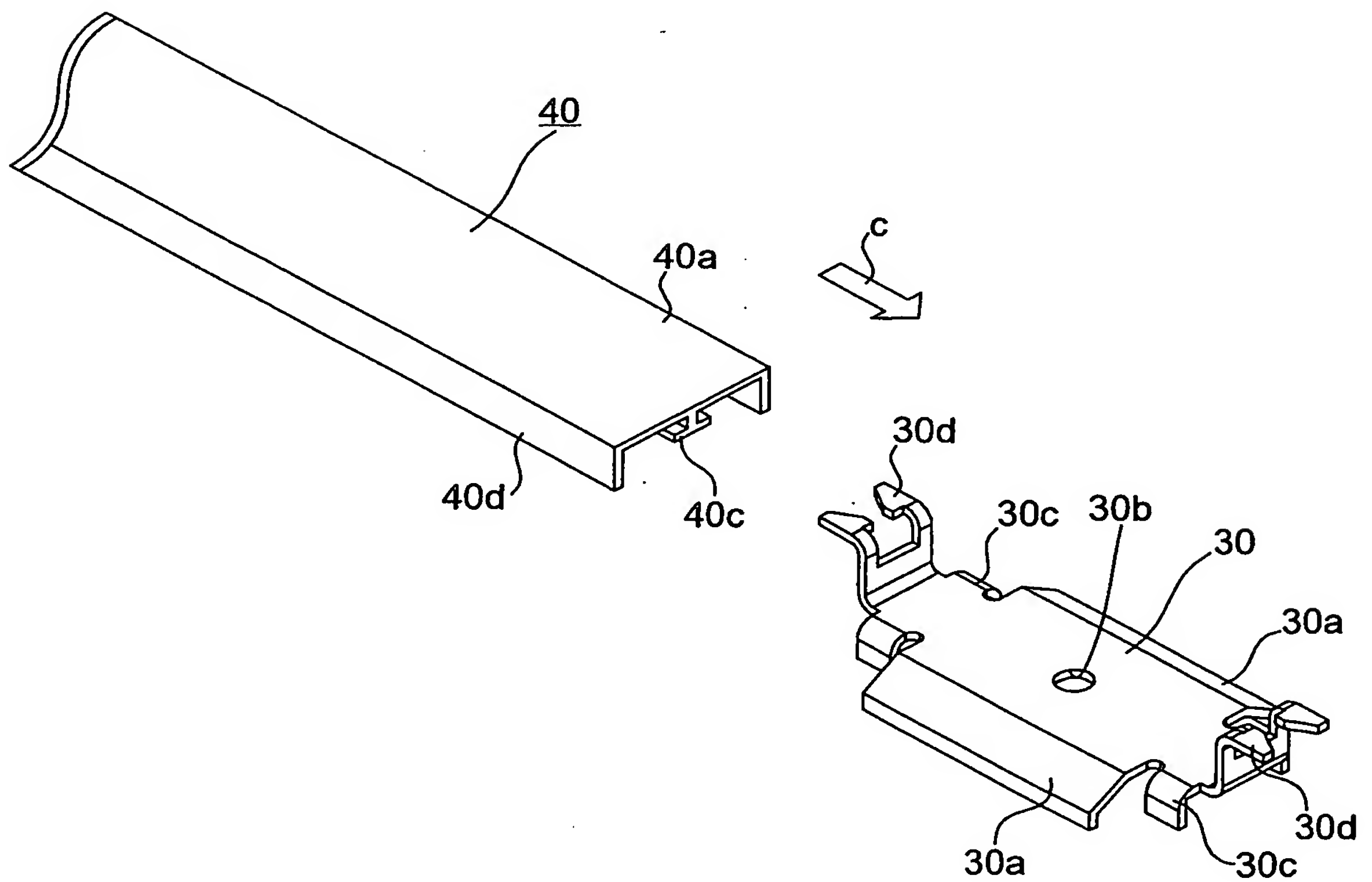


FIG.8



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FIG.9

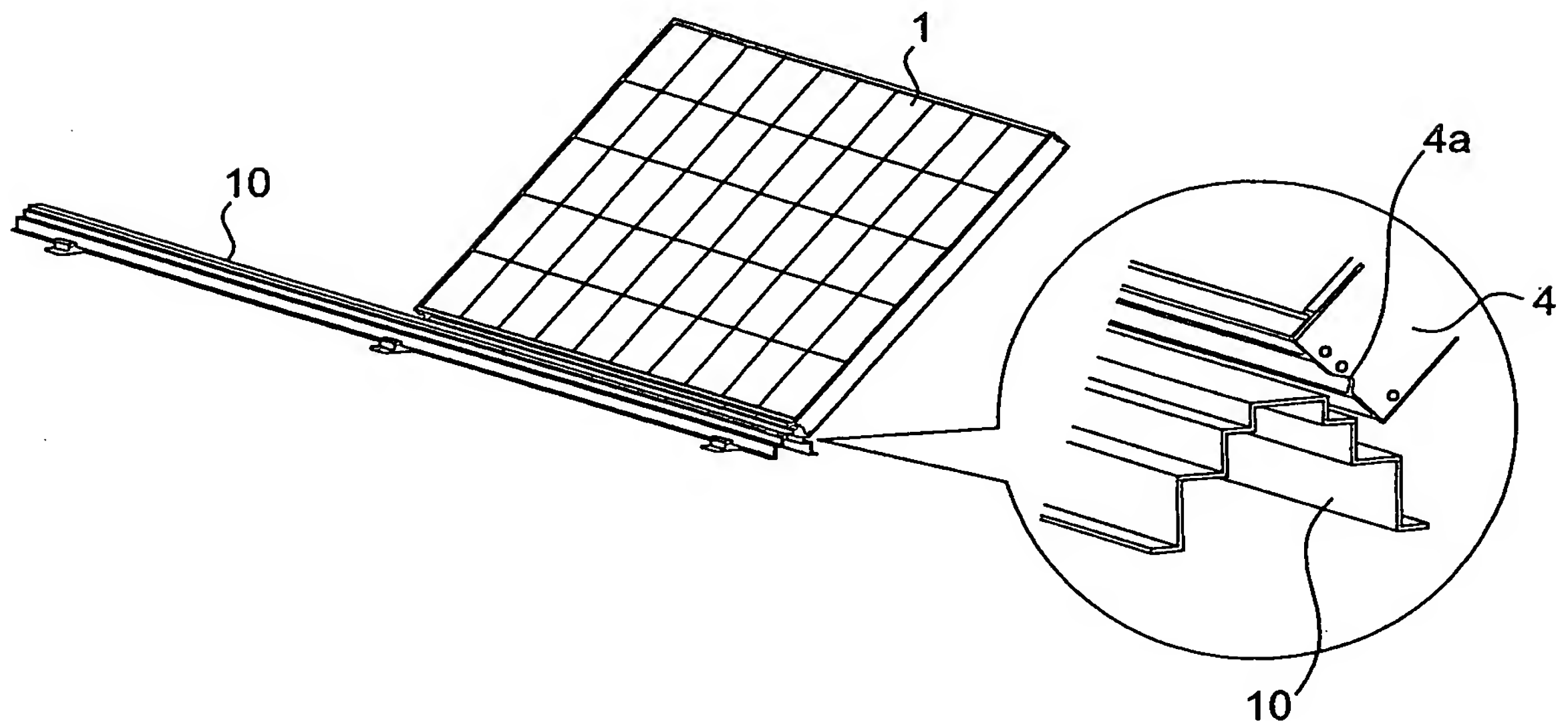
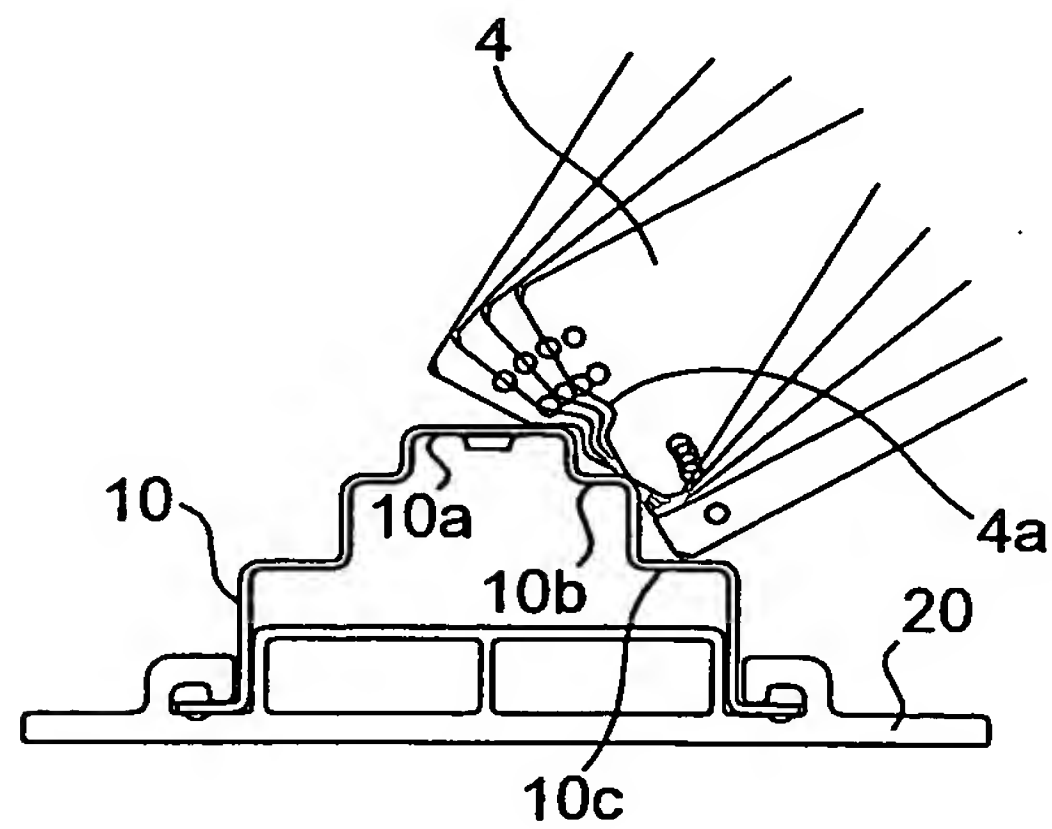


FIG.10





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FIG.11

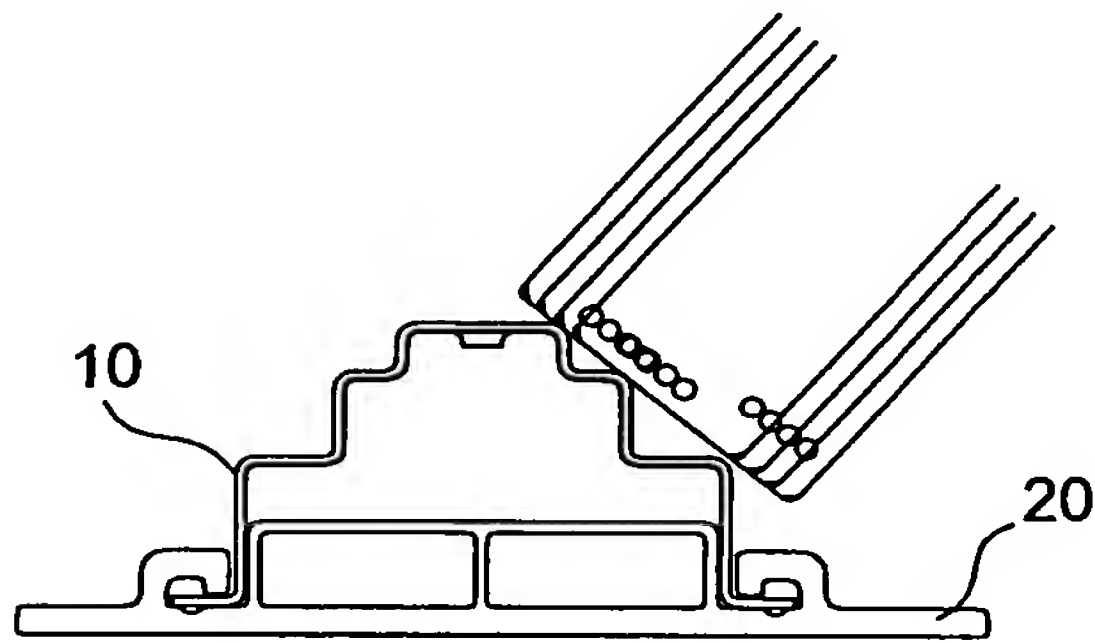
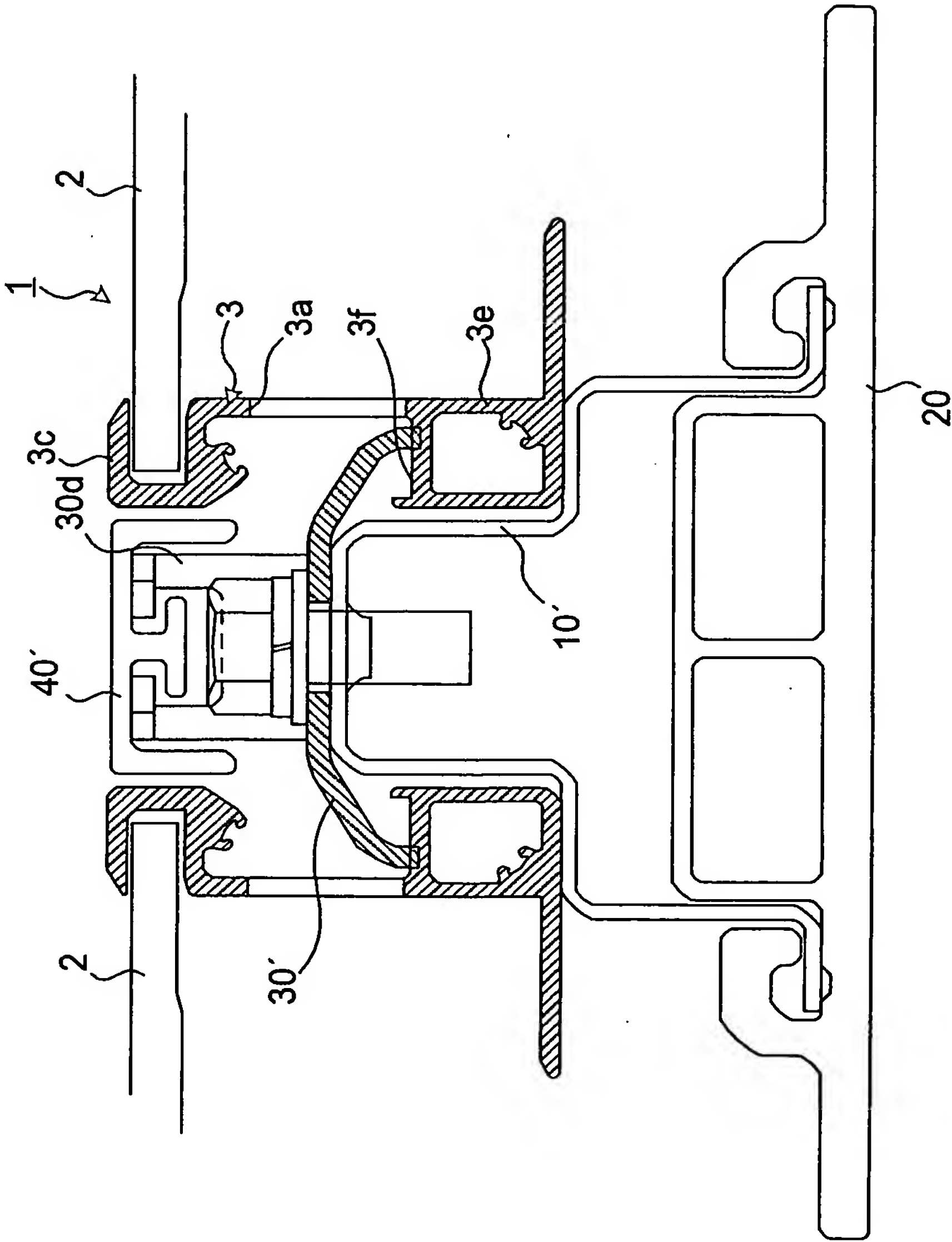
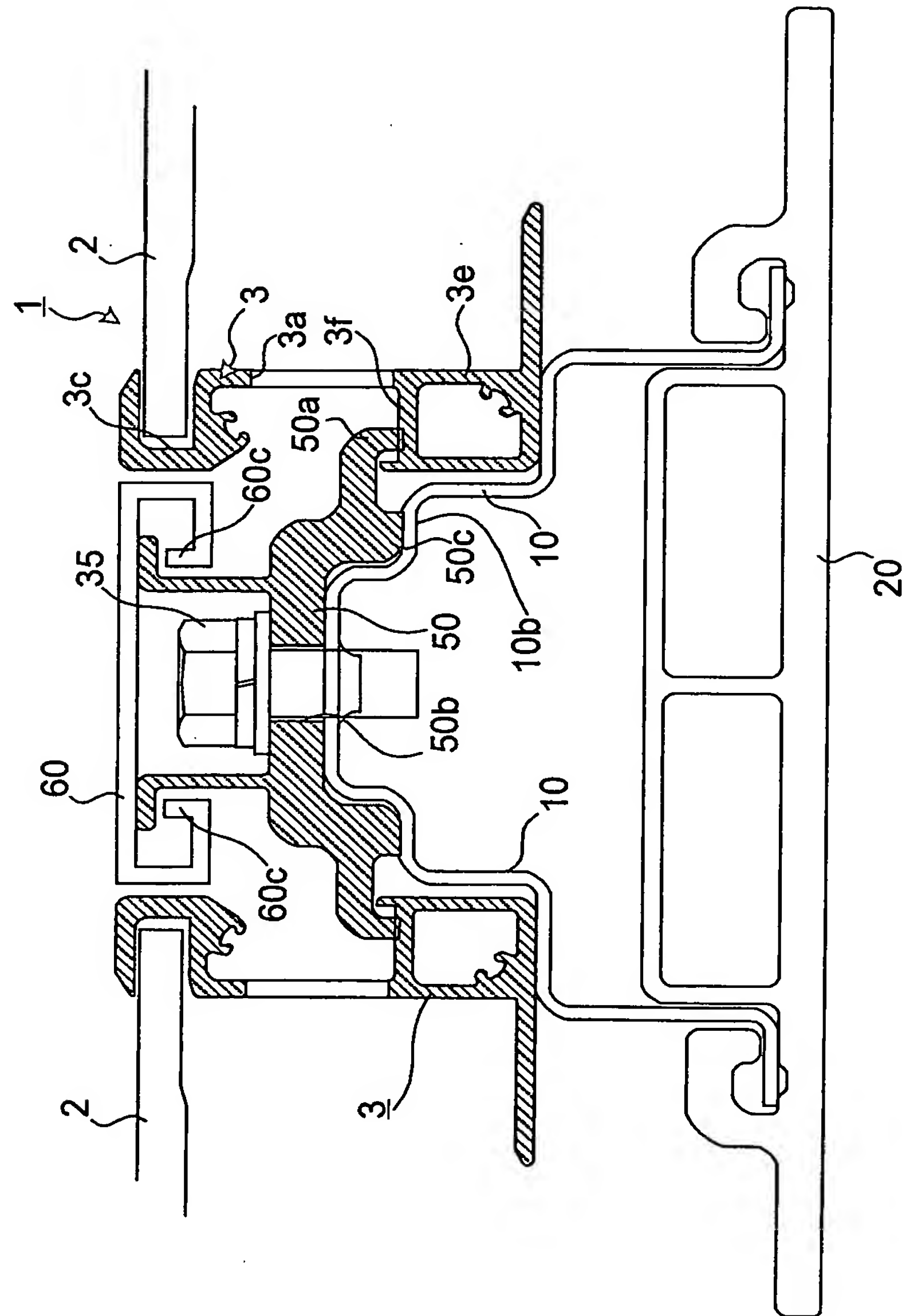


FIG. 12

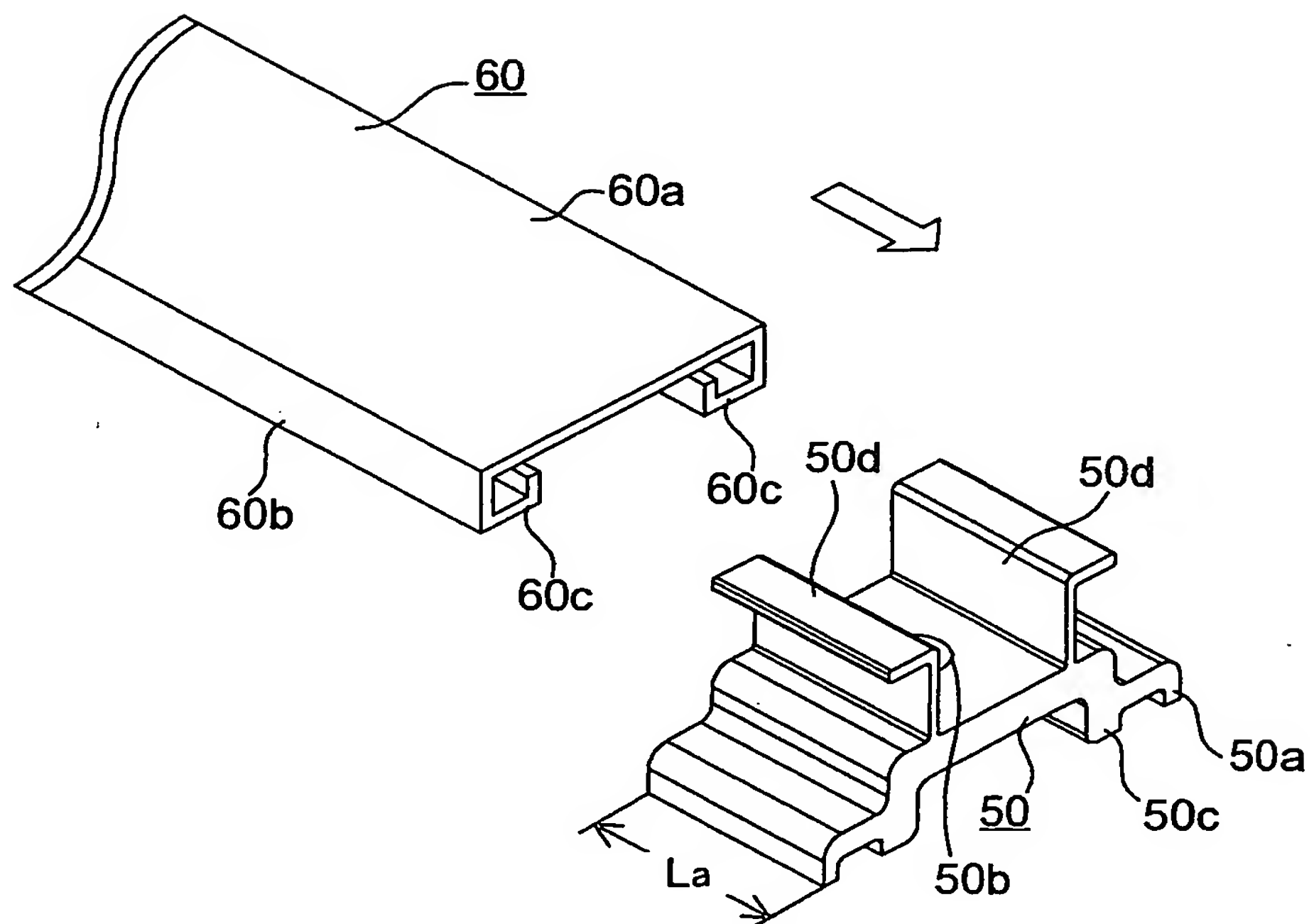


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FIG.14



This cross-sectional diagram illustrates a multi-layered electronic assembly. At the base is a substrate 110, characterized by a grid of circular vias. A thick, cross-hatched layer 103 is positioned directly above the substrate. A central vertical conductor 102 passes through the substrate and the cross-hatched layer. Above this layer is a main body 101, also shown in cross-hatched section, which features three horizontal slots on each side. A horizontal layer 105 is situated above the main body. A central vertical conductor 104 passes through this layer and is secured by a nut 104 at the top. A horizontal layer 106 is located between the main body 101 and the layer 105. On the left and right sides, horizontal conductive traces 100 are shown, with one trace on each side passing through a slot in the main body 101. The top surface of the main body 101 is divided into two regions, 101a and 101b, separated by a vertical boundary 103a.

